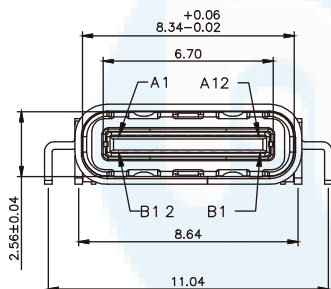
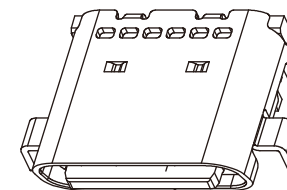
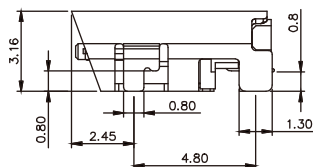
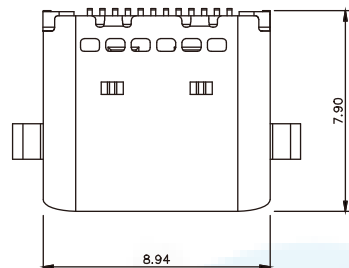
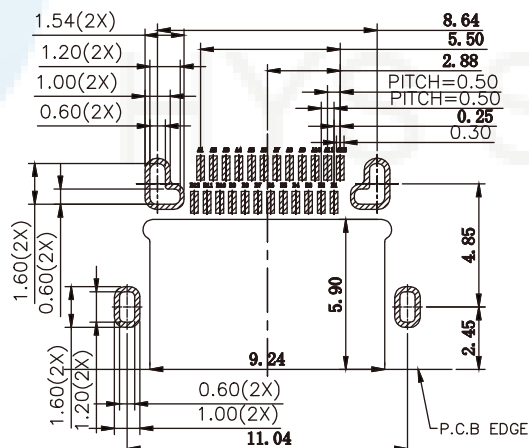
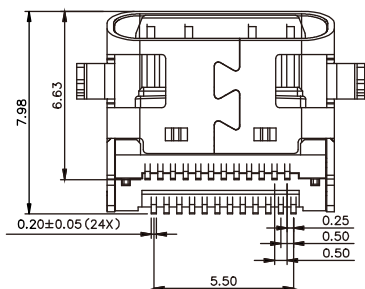


ROHS
Compatible



截面A-A



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS 0.60MM; DEFAULT TOLERANCE: ± 0.05

NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
- 2.CONTACTS: COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL
- 5.EMI PLATE: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

Ni 30u" MIN. UNDER PLATED OVER ALL.

2-3.MID PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 5~20N.
- 3-2.REMOVAL FORCE: 8~20N.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1. CURRENT RATING: 5.0A
VOLTAGE RATING: 5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mΩ

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°~+85°.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

DESIGN	Li Jinwei	SCALL	
DRAWING	Wu Qifa	UNIT	mm
CHECK	Zheng Jinxian	SIZE	A4: 210 * 297
APPROVAL	Liu Xiaohong	DATE	2020-06-10

$\varnothing$	
TOLERANCE	
X.X	± 0.30
.XX	± 0.20
.XXX	± 0.10
X.°	$\pm 2^\circ$
.X°	$\pm 1^\circ$
.XX°	$\pm 0.5^\circ$

DRAWG NO.	TYPE-C-CDSI24P080
TITLE:	24P沉板0.8四脚插板双SMT 斜口 7.9L

 **东莞市宏煜盛实业有限公司**
Dongguan hongyusheng Industry Co., Ltd
EL: 0769-81230179 <https://www.hystypec.com>